

AMENDMENTS TO THE CLAIMS

1. **(Currently Amended)** A circuit board including chip components mounted thereon, the circuit board comprising:

a substrate including electrode patterns formed thereon;

plural first chip components having a first side and a second side opposite the first side, the first side mounted through conductive bonding material on said substrate, said plural first chip components included in said chip components and including a first chip component and a second chip component; ~~and~~

a third chip component having a first electrode and a second electrode, and which is included in said chip components, said third chip component being mounted ~~through conductive bonding material by solder~~ on said second side of said plural first chip components; ~~and~~

a reinforcing resin configured to cover junctions between said plural first chip components and said third chip component on said substrate;

wherein said first chip component and said second chip component have substantially a same height on said substrate, and said third chip component is bonded ~~at by~~ said first electrode ~~to coming into direct contact with~~ an electrode of said first chip component and is bonded ~~at by~~ said second electrode ~~to coming into direct contact with~~ an electrode of said second chip component such that a longitudinal axis of said third chip component is arranged orthogonally to a longitudinal axis of each of said first chip component and said second chip component, and said plural first chip components and said third chip component are passive devices.

2. **(Previously Presented)** The circuit board according to Claim 1, wherein each of said plural first chip components and said third chip component have lengths of 2 mm or less.

3. **(Previously Presented)** The circuit board according to Claim 1, wherein each of said plural first chip components and said third chip component are resistors, condensers or inductors.

4. **(Cancelled)**

5. (Currently Amended) A circuit board including chip components mounted thereon, the circuit board comprising:

a substrate including electrode patterns formed thereon;

first chip components which are included in said chip components and mounted through a conductive bonding material on said substrate, said first chip components including a first chip component; ~~and~~

a second chip component which is included in said chip components and mounted ~~through a conductive bonding material by solder~~ on a side of said first chip components opposite from said substrate; and

a reinforcing resin configured to cover junctions between said first chip components and said second chip component on said substrate;

wherein said first chip component included in said first chip components is a component of a different type from ~~the said~~ second chip component, and said second chip component is bonded by coming into direct contact ~~to with~~ an electrode of said first chip component such that a longitudinal axis of said second chip component is arranged orthogonally to a longitudinal axis of said first chip component.

6-18. (Cancelled)